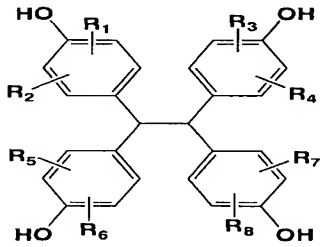
AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (currently amended): A photosensitive resin composition ~~containing~~ comprising a resin (A) soluble in an aqueous alkaline solution, a crosslinking agent (B), a photopolymerization initiator (C), and a curing agent (D), wherein the curing agent (D) is an epoxy compound obtained by glycidylating a compound containing not less than 80% of a tetraphenylethane derivative represented by formula (1):

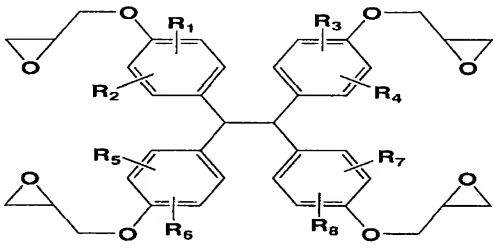


(1)

{wherein R_1 to R_8 each independently represents a hydrogen atom, a C_1 to C_4 alkyl group, or a halogen atom}.

Claim 2 (original): The photosensitive resin composition according to Claim 1, wherein the epoxy compound, which is the curing agent (D), is a compound obtained by glycidylating a tetraphenylethane derivative represented by formula (1) wherein each R_1 to R_8 is a hydrogen atom, and the compound has an epoxy equivalent of 120 to 200 g/equivalent.

Claim 3 (currently amended): The photosensitive resin composition according to Claim 1, wherein the epoxy compound, which is the curing agent (D), includes a compound represented by formula (2):



(2)

~~{~~wherein R_1 to R_8 each independently represents a hydrogen atom, a C_1 to C_4 alkyl group, or a halogen atom~~}~~ and the content of the compound in the curing agent (D) is not less than 60 mole percent.

Claim 4 (currently amended): The photosensitive resin composition according to ~~any one of Claims 1 to 3~~claim 1, wherein the curing agent (D) has a softening point or melting point of not less than 80°C.

Claim 5 (currently amended): The photosensitive resin composition according to ~~any one of Claims 1 to 3~~claim 1, wherein the curing agent (D) has a light transmittance at 400 nm of not less than 10% in a 1 weight percent methyl ethyl ketone solution.

Claim 6 (currently amended): The photosensitive resin composition according to ~~any one of Claims 1 to 5~~claim 1, wherein the resin (A) soluble in the aqueous alkaline solution is a reaction product between an epoxy carboxylate compound obtained by reaction of an epoxy compound (a) having two or more epoxy groups per molecule with a monocarboxylic acid (b) having an ethylenic unsaturated group per molecule, and a polybasic acid anhydride (c).

Claim 7 (currently amended): The photosensitive resin composition according to ~~any one of Claims 1 to 5~~claim 1, wherein the resin (A) soluble in the aqueous alkaline solution is a reaction product between an epoxy carboxylate compound obtained by reaction of an epoxy compound (d) having two epoxy groups per molecule with a monocarboxylic acid (b) having an ethylenic unsaturated group per molecule, a diisocyanate compound (e), a carboxylic acid (f) having two hydroxyl groups per molecule, and, as an optional component, a diol compound (g).

Claim 8 (currently amended): A cured product of the photosensitive resin composition according to ~~any one of Claims 1 to 7~~claim 1.

Claim 9 (original): A substrate comprising a layer composed of the cured product according to Claim 8.

Claim 10 (original): An article comprising the substrate according to Claim 9.

Claim 11 (new): The photosensitive resin composition according to claim 2, wherein the curing agent (D) has a softening point or melting point of not less than 80°C.

Claim 12 (new): The photosensitive resin composition according to claim 2, wherein the curing agent (D) has a light transmittance at 400 nm of not less than 10% in a 1 weight percent methyl ethyl ketone solution.

Claim 13 (new): The photosensitive resin composition according to claim 2, wherein the resin (A) soluble in the aqueous alkaline solution is a reaction product between an epoxy carboxylate compound obtained by reaction of an epoxy compound (a) having two or more epoxy groups per molecule with a monocarboxylic acid (b) having an ethylenic unsaturated group per molecule, and a polybasic acid anhydride (c).

Claim 14 (new): The photosensitive resin composition according to claim 2, wherein the resin (A) soluble in the aqueous alkaline solution is a reaction product between an epoxy carboxylate compound obtained by reaction of an epoxy compound (d) having two epoxy groups per molecule with a monocarboxylic acid (b) having an ethylenic unsaturated group per molecule, a diisocyanate compound (e), a carboxylic acid (f) having two hydroxyl groups per molecule, and, as an optional component, a diol compound (g).

Claim 15 (new): A cured product of the photosensitive resin composition according to claim 2.

Claim 16 (new): A substrate comprising a layer composed of the cured product according to Claim 15.

Claim 17 (new): An article comprising the substrate according to Claim 16.

Claim 18 (new): The photosensitive resin composition according to claim 3, wherein the curing agent (D) has a softening point or melting point of not less than 80°C.

Claim 19 (new): The photosensitive resin composition according to claim 3, wherein the curing agent (D) has a light transmittance at 400 nm of not less than 10% in a 1 weight percent methyl ethyl ketone solution.

Claim 20 (new): The photosensitive resin composition according to claim 3, wherein the resin (A) soluble in the aqueous alkaline solution is a reaction product between an epoxy carboxylate compound obtained by reaction of an epoxy compound (a) having two or more epoxy groups per molecule with a monocarboxylic acid (b) having an ethylenic unsaturated group per molecule, and a polybasic acid anhydride (c).

Claim 21 (new): The photosensitive resin composition according to claim 3, wherein the resin (A) soluble in the aqueous alkaline solution is a reaction product between an epoxy carboxylate compound obtained by reaction of an epoxy compound (d) having two epoxy groups per molecule with a monocarboxylic acid (b) having an ethylenic unsaturated group per molecule, a diisocyanate compound (e), a carboxylic acid (f) having two hydroxyl groups per molecule, and, as an optional component, a diol compound (g).

Claim 22 (new): A cured product of the photosensitive resin composition according to claim 3.

Claim 23 (new): A substrate comprising a layer composed of the cured product according to Claim 22.

Claim 24 (new): An article comprising the substrate according to Claim 23.